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Ongoing activities at CiS

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The CiS research institute is engaged in developments of radiation detector technologies on several different fields. Current projects are dealing e.g. with large area thinned sensors, active edge sensors, sensor-chip packaging technologies and defect engineering.
For large area sensors, the need for smaller thicknesses can be approached by etching cavities to the sensors back side while guaranteeing stability on wafer level by thick frames at the edges. A first n-in-p pixel run with membranes up to 4x4cm² is finished and shows promising results. An active edge sensor run is currently ongoing. The status of the production, especially results of the challenging ICP trench etching step will be shown.

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